

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S2	64	uzoh.in. and international adj business	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 11:03
S6	0	electro adj chemical adj mechanical adj machining and weir	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 11:04
S5	0	"electro-chemical mechanical machining" and weir	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 11:04
S4	0	"electrochemical mechanical machining" and weir	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 11:04
S3	0	uzoh.in. and international adj business and weir	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 11:04
S10	1	electro adj chemical adj mechanical adj machining	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 11:05
S9	27	electro adj chemical adj mechanical adj polishing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 11:05
S8	1	electro adj chemical adj mechanical adj polishing and weir	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 11:05
S7	29249	electro adj chemical adj mechanical adj polishingand weir	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 11:05
S13	4378	eddy adj current with (sensor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 11:08

S12	5	((electro adj chemical) electrochemical) adj mechanical adj (polishing machining) and weir	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 11:08
S14	1158	eddy adj current with (sensor) with coil	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 13:47
S17	28	eddy adj current with (sensor) with coil with core and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 13:48
S16	409261	eddy adj current with (sensor) with coil with core and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 13:48
S15	129	eddy adj current with (sensor) with coil and wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 13:48
S19	2	("6811680" "6878038").pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/24 14:38
S18	22	("20020077031" "4303885" "4467281" "4556845" "4715007" "4716366" "4829251" "5003262" "5213655" "5237271" "5343146" "5355083" "5511005" "5541510" "5559428" "5644221" "5660672" "5731697" "6120348" "6407546" "6563308" "RE35703").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/24 14:38
S22	2	"20020119286".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 15:03
S21	0	"200200119286".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 15:03
S20	11	polishing adj pad with layer with (anod\$2 cathod\$2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 15:03

S11	198	((electro adj chemical) electrochemical) adj mechanical adj (polishing machining)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 15:19
S24	4298	(sphere ball) with contact with (substrate wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 15:21
S23	35	ECMP and (sphere ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 15:21
S25	38	(sphere ball) with contact with (substrate wafer) and ("204" "205"). clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 15:30
S26	3	"6402925".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 15:38
S27	192	polishing adj pad same (anod\$2 cathod\$2)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/24 16:00